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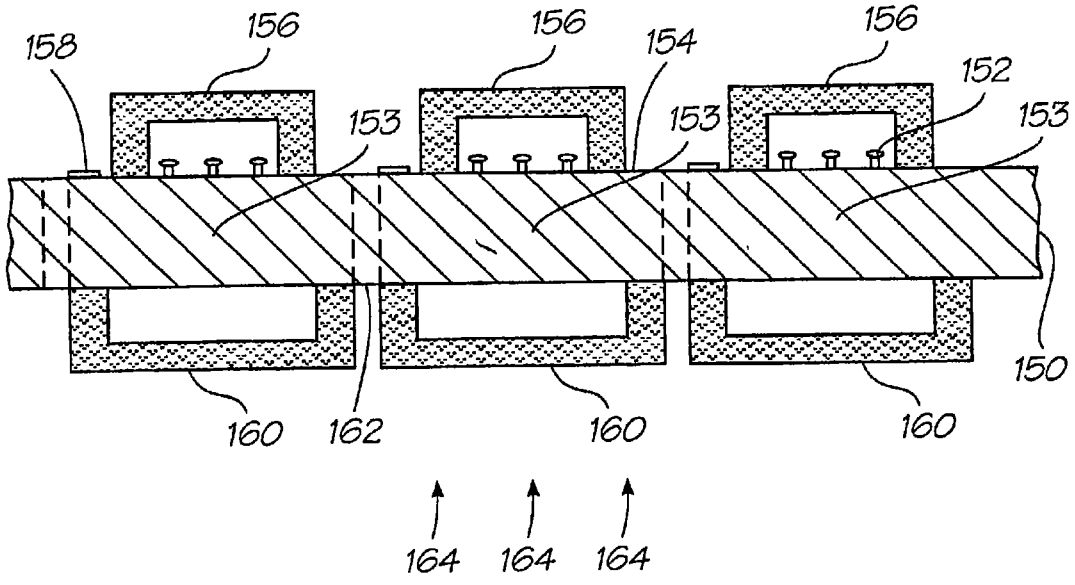
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(54) Title: USE OF PROTECTIVE CAPS AS MASKS AT A WAFER SCALE



(57) Abstract: Caps (156, 160) are bonded to one or both sides of a wafer (150) to overlay in plan view all or part of a microfabricated device or group of devices (152). One or more etches (164) are applied from the cap side to remove material and to separate the wafer (150) into discrete units.

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